

PATENT ASSIGNMENT

Electronic Version v1.1

Stylesheet Version v1.1

SUBMISSION TYPE:	NEW ASSIGNMENT						
NATURE OF CONVEYANCE:	ASSIGNMENT						
CONVEYING PARTY DATA							
<table border="1"><thead><tr><th>Name</th><th>Execution Date</th></tr></thead><tbody><tr><td>Yeong-Gyu Lee</td><td>10/22/2004</td></tr><tr><td>Seung-Do An</td><td>10/22/2004</td></tr></tbody></table>	Name	Execution Date	Yeong-Gyu Lee	10/22/2004	Seung-Do An	10/22/2004	
Name	Execution Date						
Yeong-Gyu Lee	10/22/2004						
Seung-Do An	10/22/2004						
RECEIVING PARTY DATA							
Name:	Samsung Electro-Mechanics Co., Ltd.						
Street Address:	314, Maetan-3dong						
City:	Youngtong-gu, Suwon-si, Kyunggi-do						
State/Country:	KOREA, REPUBLIC OF						
Postal Code:	443-743						
PROPERTY NUMBERS Total: 1							
<table border="1"><thead><tr><th>Property Type</th><th>Number</th></tr></thead><tbody><tr><td>Application Number:</td><td>10953120</td></tr></tbody></table>	Property Type	Number	Application Number:	10953120			
Property Type	Number						
Application Number:	10953120						
CORRESPONDENCE DATA							
Fax Number:	(206)224-0779						
<i>Correspondence will be sent via US Mail when the fax attempt is unsuccessful.</i>							
Phone:	2066828100						
Email:	efiling@cojk.com						
Correspondent Name:	Jerald E. Nagae, Esq.						
Address Line 1:	Christensen O'Connor Johnson Kindness						
Address Line 2:	1420 Fifth Avenue, Suite 2800						
Address Line 4:	Seattle, WASHINGTON 98101-2347						
NAME OF SUBMITTER:	Jerald E. Nagae						
Total Attachments: 2 source=23670Assignment#page1.tif source=23670Assignment#page2.tif							

CH \$40.00 10953120

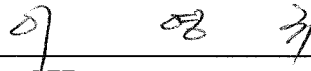
ASSIGNMENT

WHEREAS, we, Yeong-Gyu LEE, residing at 306-703, LG Village, Geumgok-dong, Gwonseon-gu, Suwon-si, Kyunggi-do 441-704, Korea; and Seung-Do AN, residing at 206-606, Woncheon Jugong Apt., Woncheon-dong, Yeongtong-gu, Suwon-si, Kyunggi-do 443-756, Korea, are the inventors named in an application for Letters Patent of the United States, entitled SEMICONDUCTOR PACKAGE AND PACKAGING METHOD USING FLIP-CHIP BONDING TECHNOLOGY, we hereby authorize our attorneys of the firm Christensen O'Connor Johnson Kindness^{PLLC}, 1420 Fifth Avenue, Suite 2800, Seattle, Washington 98101, to insert here in parentheses (Application No. 10/953,120) the application number of said application;

AND, WHEREAS, Samsung Electro-Mechanics Co., Ltd., a Korea corporation, having an address at 314, Maetan-3dong, Youngtong-gu, Suwon-si, Kyunggi-do 443-743, Republic of Korea (hereinafter referred to as ASSIGNEE), is desirous of acquiring our entire right and title to and interest in our invention disclosed in said application;

NOW, THEREFORE, for sufficient, good and valuable consideration, the receipt of which is hereby acknowledged, we do hereby sell, assign and transfer unto ASSIGNEE our entire right and title to and interest in said application and said invention, including the right to apply for international patents and patents thereon in foreign countries in our name or in the name of ASSIGNEE, said invention and all applications and patents on said invention to be held and enjoyed by ASSIGNEE as entirely as the same would have been held and enjoyed by us had this sale, assignment and transfer not been made, and we do hereby further agree and promise to execute all instruments and render all such assistance as ASSIGNEE may request in order to make and prosecute any and all applications on said invention, to enforce any and all patents on said invention, and to confirm in ASSIGNEE legal title to said invention and all applications and patents on said invention, all without charge to ASSIGNEE but at no expense to us.


Executed at Kyunggi-do, Korea, this 22nd day of October, 2004.

x 
Yeong-Gyu LEE

WITNESS:

I certify that I know or have satisfactory evidence that Yeong-Gyu LEE is the person who appeared before me, and that he acknowledged that he signed this instrument and acknowledged it to be his free and voluntary act for the uses and purposes mentioned in the instrument.

Dated: October 22, 2004

x 
Signature

Printed Name:

KWON, OH-JIN

Executed at Kyunggi-do, Korea, this 22nd day of October, 2004.

x Seung-Do AN
Seung-Do AN

WITNESS:

I certify that I know or have satisfactory evidence that Seung-Do AN is the person who appeared before me, and that he acknowledged that he signed this instrument and acknowledged it to be his free and voluntary act for the uses and purposes mentioned in the instrument.

Dated: October 22, 2004

x Signature
Signature

Printed Name:

KWON, OH-JIN

JEN:hjd